



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q64636

Olivier VENDIER, et al.

Appln. No.: 09/865,720

Group Art Unit: 2877

Confirmation No.: 5944

Examiner: Kaveh C. KIANNI

Filed: May 29, 2001

For: AN ELECTRONIC ASSEMBLY HAVING HIGH INTERCONNECTION DENSITY

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated February 27, 2003, please amend the above-identified application as follows:

**IN THE CLAIMS:**

**Please enter the following amended claims:**

1. (Amended) An electronic assembly comprising at least a first integrated electronic module, the first module including at least one interconnection means for optical connection to a printed circuit card or to a second electronic module, the assembly including a soleplate and heat removal means for removing heat from the first module, the soleplate being independent of the interconnection means of the first module, and wherein the soleplate is independent of the interconnection means of the first module.

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